

## Soldered SAM data sheet SAM-λ-A-τ-4.0-25.4s-c or 4.0-25.4s-e

GaAs chip area                     standard:       4.0 mm x 4.0 mm  
   optional:       other dimensions on request

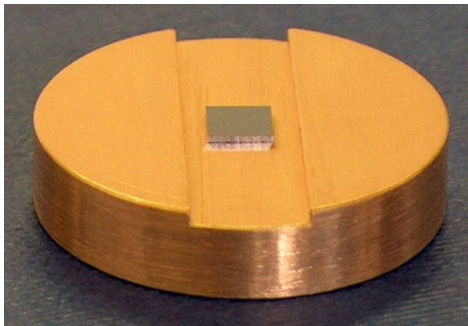
Chip thickness                     standard:       450 μm

Front side protection             the SAM is protected with a dielectric front layer.

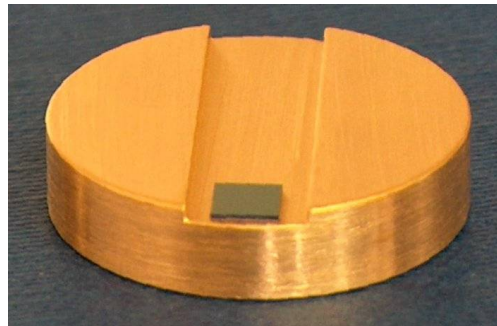
The SAM chip is soldered on a gold plated Cu-cylinder with 25.4 mm Ø using a Sn/Bi solder . The solder ensures a low thermal resistance between the SAM and the heat sink.

- The **standard** position of the SAM is at the center of the mount → x = 4.0-25.4s-c.
- **Optional** the SAM can be mounted at the edge of the mount without extra charges.  
→ x = 4.0-25.4s-e.

Center mounted SAM



Edge mounted SAM



### Mount

Cu-cylinder, Ø = 25.4 mm  
l = 6.0 mm

